

Report on the Chinese Semiconductor sealants Market 2019-2023

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Abstracts

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The semiconductor seal material market is a supporting industry of the semiconductor market and the seal material testing market. Classic examples of seal materials include machine substrates, lead frames, plastic seals, underfill materials, bonding wire, liquid bonding substances, solder balls, chip glue and more. These materials are used to protect microchips and increase heat transfer capability as well as connect chips to external circuits.

The development history of seal materials indicates that seal materials are play an important part of innovation in seal technology, with the former dictating the pace of technological innovation of the latter. Seal material trends are mostly converging towards miniaturization due to the demand for such in downstream products. Japanese and American companies serve as a guiding force in the global seal material market, while Chinese companies almost exclusively rely on imports for high quality products

The surge in demand for semiconductor products has also led to a surge of demand for semiconductor seal materials to a point where supplies are currently unable to meet demands. This has caused seal material companies to use innovation and expanded production to as an answer to meet rising demands and join the global seal material market. The Chinese seal material market reached a total of XX billion CNY in scale. Innovative practices, tighter quality control and larger production lines are slowly giving Chinese companies a competitive edge in the Chinese market.

Increased production capacity, increased technology, higher demands and political support is expected to become prime driving forces for the growth of the market, which

is expected to reach a scale of XX billion CNY by 2023.

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